

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,982,492 B2
DATED : January 3, 2006
INVENTOR(S) : Christopher L. Rumer et al.

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 7, lines 30-34 and Column 8, Lines 1-14,

Insert:

9. A system comprising:

a die comprising an integrated circuit; and

a chipset in communication with the integrated circuit;

wherein the die comprises a plurality of connection bumps each bonded to a respective one of a plurality of solder bumps on a substrate, an underfill being present between the substrate and the die, the underfill being at least partially filled with filler particles, at least some of the filler particles being electrically conductive;

wherein the filler particles include non-conductive particles and conductive particles; wherein:

the non-conductive particles constitute at least 20% and not more than 40% by volume of the composition; and

the conductive particles constitute at least 10% and not more than 20% by volume of the composition.

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Column 8.

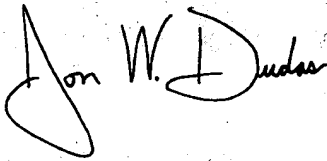
Lines 15-25, insert:

10. A device comprising:

- a substrate having a plurality of bumps;
- a die having a plurality of bumps each bonded to a respective one of the bumps of the substrate; and
- an underfill between the substrate and the die, the underfill being at least partially filled with filler particles;
 - wherein the filler particles include non-conductive particles and conductive particles;
 - wherein the non-conductive particles do not exceed 50% by volume of the underfill and the conductive particles do not exceed 30% by volume of the underfill.

Signed and Sealed this

Eleventh Day of April, 2006

A handwritten signature in black ink, reading "Jon W. Dudas", is written over a faint rectangular grid background.

JON W. DUDAS
Director of the United States Patent and Trademark Office